

Application No. 09/676,696

a fiber coupling assembly having a barrel which operably engages a fiber optic cable; and

an alignment guide structure for passively aligning said fiber coupling assembly with said optoelectronic device.

A2  
Cmld

REMARKS


Applicant has amended claims 1 22, 38, 46 and 47 for clarity and added claims 49-56 to claim additional subject matter to which applicant is entitled. Applicants respectfully request entry of the present amendment and examination and allowance of this application.

Attached hereto is a marked-up version of the changes made to the claims by the current amendment. The attached page is captioned "Version with markings to show changes made."

Respectfully submitted,

CHRISTIE, PARKER & HALE, LLP

By



Peter A. Nichols  
Reg. No. 47,822  
626/795-9900

PAN/cks



VERSION WITH MARKINGS TO SHOW CHANGES MADE

1. (Amended) An optical device package comprising:  
an optoelectronic device, comprising a mounting surface  
operably coupled to a surface of a substrate and an active surface  
that emits or receives light, wherein said active surface of said  
optoelectronic device is substantially parallel to said substrate and  
[7] wherein said optoelectronic device is in electrical communication  
with said substrate; and  
an enclosure coupled to said substrate, that houses said  
optoelectronic device.

22. (Amended) The optical device package of claim 1 wherein said  
optoelectronic device comprises an integrated transceiver, wherein  
said transceiver comprises a transmitter, a power monitoring  
photodetector and a photodiode [~~reciever~~] receiver.

38. (Amended) The optical device package of claim 1 further  
comprising:  
a fiber coupling assembly having a barrel which operably  
engages a fiber optic cable; and  
an alignment guide structure for passively aligning said  
fiber coupling assembly with said [~~optical~~] optoelectronic device.

46. (Amended) The optical device package of claim 45 wherein  
said substrate [~~is~~] comprises a flex-rigid circuit board, and wherein  
said flex-rigid circuit board comprises a daughter board coupled to  
a mother board by a flexible substrate.

47. (Amended) A method of packaging an optoelectronic device  
comprising the steps of:  
operably [~~mounting an~~] coupling a mounting surface of an  
optoelectronic device on a surface of a substrate, wherein an active

RECEIVED  
SEP 7 2001  
TC 2880 MAIL ROOM

Application No. 09/676,696

surface of said optoelectronic device that emits or receives light is substantially parallel to said substrate surface;

electrically coupling the optoelectronic device to said substrate;

sealing the optoelectronic device.

CKS PAS376539.1-\*--8/31/01 12:02 PM